



2A SURFACE MOUNT GLASS PASSIVATED BRIDGE RECTIFIER

FEATURES:

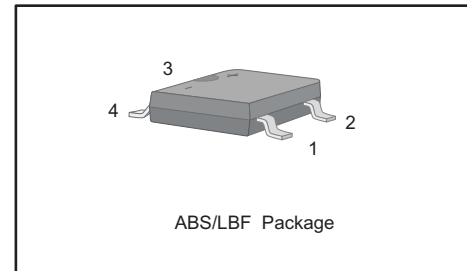
- Glass Passivated Chip Junction
- Reverse Voltage - 1000 V
- Forward Current - 2.0 A
- Fast reverse recovery time
- Designed for Surface Mount Application

MECHANICAL DATA

- Case: ABS/LBF
- Terminals: Solderable per MIL-STD-750, Method 2026
- Approx. Weight: 88mg/0.0031oz

PINNING

PIN	DESCRIPTION
1	Input Pin (~)
2	Input Pin (~)
3	Output Anode (+)
4	Output Cathode (-)



Maximum Ratings and Electrical characteristics

Ratings at 25 °C ambient temperature unless otherwise specified.

Single phase half-wave 60 Hz, resistive or inductive load, for capacitive load current derate by 20 %.

Parameter	Symbols	FTB10SH-20	Units
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	1000	V
Maximum RMS voltage	V_{RMS}	700	V
Maximum DC Blocking Voltage	V_{DC}	1000	V
Maximum Average Forward Rectified Current @ Fig.1	$I_{F(AV)}$	2.0	A
Peak Forward Surge Current,8.3ms Single Half Sine-wave Superimposed on Rated Load (JEDEC method)	I_{FSM}	60	A
Peak Forward Surge Current,1.0ms Single Half Sine-wave Superimposed on Rated Load (JEDEC method)	I_{FSM}	120	A
I^2t Rating for fusing ($3ms \leq t \leq 8.3ms$)	I^2t	14.9	A ² S
Max Instantaneous Forward Voltage at 2.0 A	V_F	1.3	V
Maximum DC Reverse Current at Rated DC Reverse Voltage $T_a = 25^\circ C$ $T_a = 125^\circ C$	I_R	5 200	μA
Typical Junction Capacitance ⁽¹⁾	C_j	20	pF
Maximum Reverse Recovery Time ⁽²⁾	t_{rr}	350	ns
Typical Thermal Resistance ⁽³⁾	$R_{\theta JA}$ $R_{\theta JC}$ $R_{\theta JL}$	40 8 20	$^\circ C/W$
Operating and Storage Temperature Range	T_j, T_{stg}	-55 ~ +150	$^\circ C$

(1) Measured at 1 MHz and applied reverse voltage of 4 V D.C

(2) Measured with $I_F = 0.5 A$, $I_R = 1 A$, $I_{rr} = 0.25 A$.

(3) P.C.B. mounted with $4 \times 1.5'' \times 1.5''$ (3.81 X 3.81 cm) copper pad areas.



Fig.1 Average Rectified Output Current Derating Curve

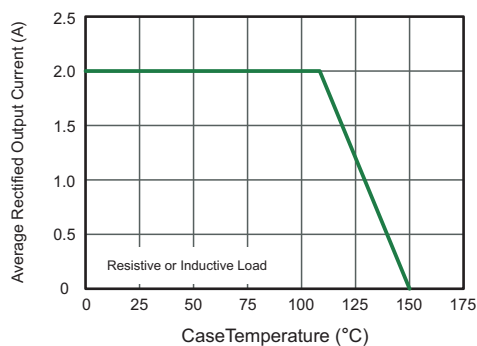


Fig.2 Typical Reverse Characteristics

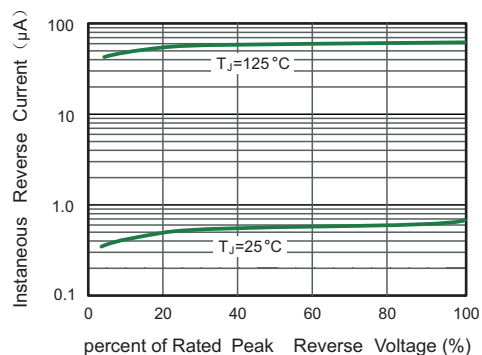


Fig.3 Typical Instantaneous Forward Characteristics

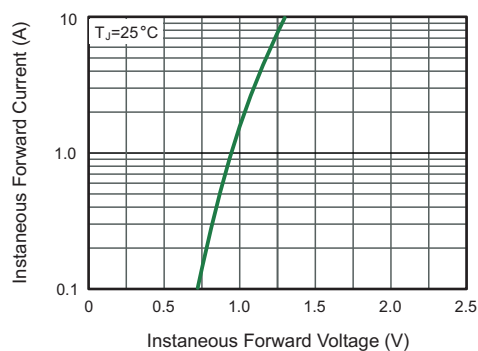


Fig.4 Typical Junction Capacitance

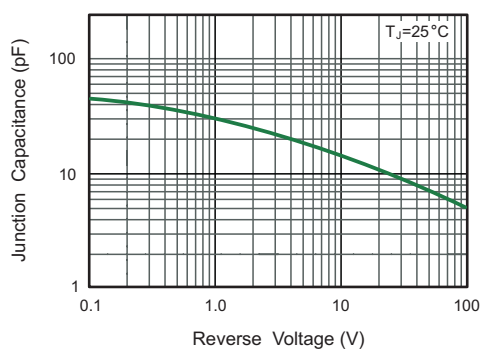
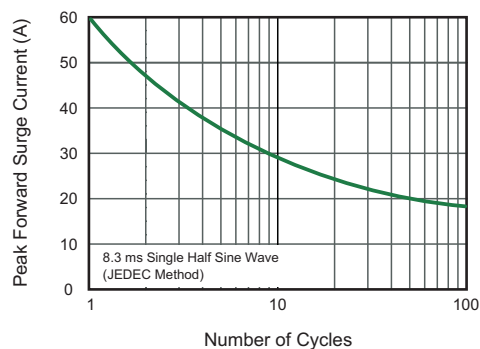


Fig.5 Maximum Non-Repetitive Peak Forward Surge Current

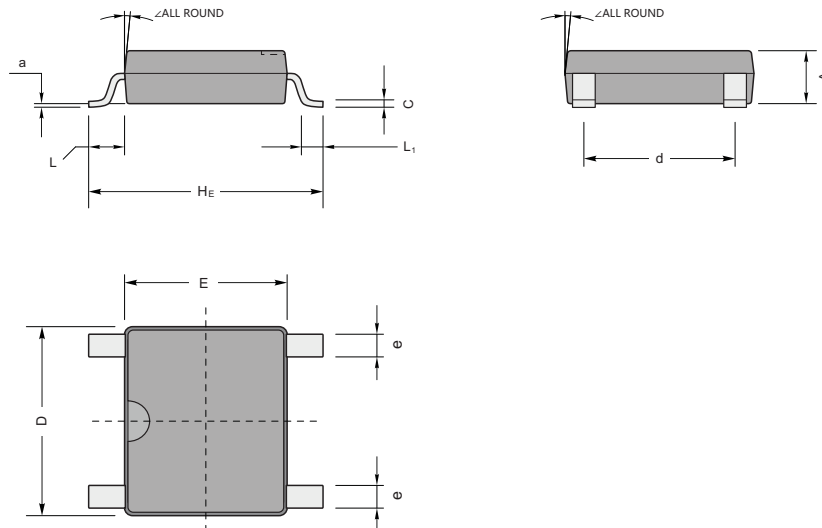




PACKAGE OUTLINE

Plastic surface mounted package; 4 leads

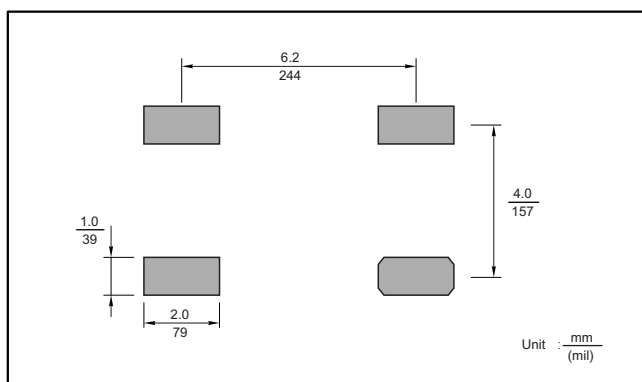
ABS/LBF



ABS/LBF mechanical data

UNIT		A	C	D	E	H _E	d	e	L	L ₁	a	∠
mm	max	1.5	0.22	5.2	4.5	6.4	4.2	0.7	0.95	0.6	0.2	7°
	min	1.3	0.15	4.9	4.2	6.0	3.8	0.5				
mil	max	59	8.7	205	177	252	165	28	37	24	8	
	min	51	5.9	193	166	236	150	20				

The recommended mounting pad size



Marking

Type number	Marking code
FTB10SH-20	F20T10



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